Announcing

EDAPS 2022 Mini-Workshop

The 1st International IEEE EDAPS Mini-Workshop on Emerging Trends in Semiconductor IC Packaging

Supported by IEEE EPS in collaboration with ELECOM 2022

22nd November 2022, 2.00-5.00pm, GMT+4

Republic of Mauritius

ELECOM 2022

IEEE EDAPS (Electrical Design of Advanced Packaging and Systems) is pleased to announce its 1st International Mini-Workshop on Emerging Trends in Semiconductor Integrated Circuit (IC) Packaging. The IEEE Electrical Design of Advanced Packaging and Systems (EDAPS) symposium has consistently served as a platform for disseminating the latest research on chip, package, and system electrical design. Designers and researchers worldwide share and discuss their work on all aspects of electrical IC packaging, including modeling, design and simulation, fabrication, and characterization. We are excited to host this workshop in IEEE Region 8. This workshop will consist of four invited keynote presentations covering multiple aspects of IC Packaging from experts in academia and industry and invited presentations from EPS Student Chapters/Chapters in Region 8. Your attendance at this event is highly encouraged as it is a forerunner to the highly anticipated EDAPS 2023 Workshop!

Organizing Committee

Dr. R. Murugan,
Texas Instruments, Inc., USA

Dr. M. Gooroochurn,
University of Mauritius,
Republic of Mauritius

Assoc Prof (Dr) T.P. Fowdur,
University of Mauritius,
Republic of Mauritius

Assoc Prof (Dr) R.T.F. Ah King,
University of Mauritius,
Republic of Mauritius

Prof. M. Swaminathan,
Georgia Tech., USA

Prof. J. Schutt-Aine,
University of Illinois, USA

Keynote Presentations

1. **Semiconductor IC Packaging, Professor Madhavan Swaminathan**
   John Pippin Chair in Microsystems Packaging & Electromagnetics, Director, 3D Systems Packaging Research Center (PRC), Georgia Tech (GT), USA
2. **IC Packaging Trends & Challenges, Professor Paul Franzon**
   Cirrus Logic Distinguished Professor; Director of Graduate Programs, North Carolina State University (NCSA), USA
3. **Trends & Challenges in IC Packaging Manufacturing**, **Dr. Tanja Braun**
   Group Leader, Fraunhofer Institute for Reliability and Microintegration, Berlin, Germany
4. **Modeling for Semiconductor Packaging and Systems** , **Dr. Hubert Harrer**
   Senior Technical Staff Member (STSM), IBM Deutschland Research & Development GmbH, Boeblingen, Germany

Student Chapters/Chapters Presentations (IEEE R8)

1. **Africa, Ethiopia:** Dr. W. Beyene (Meta) & Prof. F. Mulugeta (AAiT)
2. **Europe, United Kingdom:** Prof. Chris Bailey, EPS Chapter Chair
3. **Middle East, Israel:** Aviv Ronen, EPS Chapter Chair

Website: https://www.elecom2022.com/